OPA855 8-GHz Gain Bandwidth Product, Gain of 7-V/V Stable, Bipolar Input Amplifier

1 Features

- High Gain Bandwidth Product: 8 GHz
- Decompensated, Gain ≥ 7 V/V (Stable)
- Low Input Voltage Noise: 0.98 nV/√Hz
- Slew Rate: 2750 V/µs
- Low Input Capacitance:
  - Common-Mode: 0.6 pF
  - Differential: 0.2 pF
- Wide Input Common-Mode Range:
  - 0.4 V from Positive Supply
  - 1.1 V from Negative Supply
- 3 V_{PP} Total Output Swing
- Supply Voltage Range: 3.3 V to 5.25 V
- Quiescent Current: 17.8 mA
- Package: 8-Pin WSON
- Temperature Range: –40 to +125°C

2 Applications

- High-Speed Transimpedance Amplifier
- Laser Distance Measurement
- CCD Output Buffer
- High-Speed Buffer
- Optical Time Domain Reflectometry (OTDR)
- High-Speed Active Filter
- 3D Scanner
- Silicon Photomultiplier (SiPM) Buffer Amplifier
- Photomultiplier Tube Post Amplifier

3 Description

The OPA855 is a wideband, low-noise operational amplifier with bipolar inputs for wideband transimpedance and voltage amplifier applications. When the device is configured as a transimpedance amplifier (TIA), the 8-GHz gain bandwidth product (GBWP) enables high closed-loop bandwidths at transimpedance gains of up to tens of kΩs.

The graph below shows the bandwidth and noise performance of the OPA855 as a function of the photodiode capacitance when the amplifier is configured as a TIA. The total noise is calculated along a bandwidth range extending from dc to the calculated frequency, f, on the left-hand scale. The OPA855 package has a feedback pin (FB) that simplifies the feedback network connection between the input and the output.

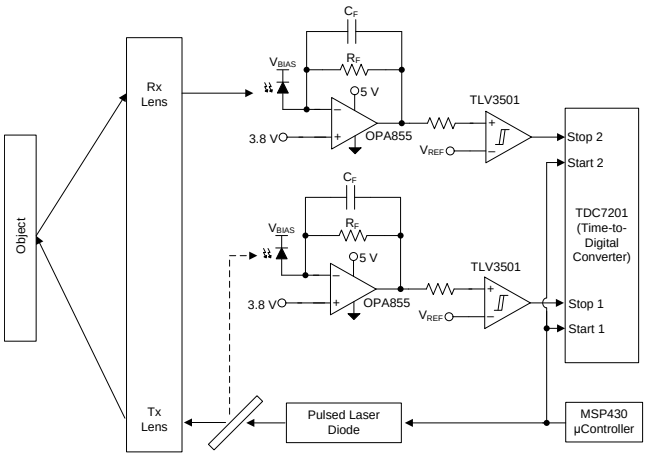
The OPA855 is optimized to operate in optical time-of-flight (ToF) systems where the OPA855 is used with time-to-digital converters, such as the TDC7201. Use the OPA855 to drive a high-speed analog-to-digital converter (ADC) in high-resolution LIDAR systems with a differential output amplifier, such as the THS4541 or LMH5401.

Device Information(1)

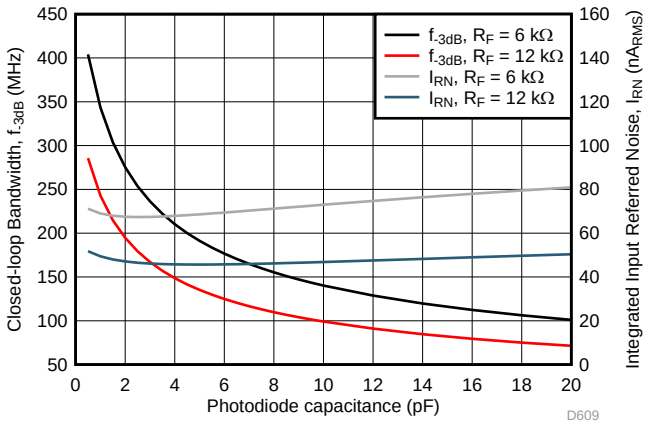
PART NUMBER	PACKAGE	BODY SIZE (NOM)
OPA855	WSON (8)	2.00 mm × 2.00 mm

(1) For all available packages, see the package option addendum at the end of the data sheet.

High-Speed Time-of-Flight Receiver



Photodiode Capacitance vs Bandwidth and Noise



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Revision History

Changes from Original (July 2018) to Revision A **Page**

- Changed from Advance Information to Production Data (active) ... 1

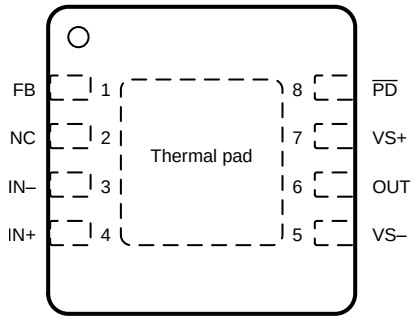
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5 Device Comparison Table

DEVICE	INPUT TYPE	MINIMUM STABLE GAIN	VOLTAGE NOISE (nV/√Hz)	INPUT CAPACITANCE (pF)	GAIN BANDWIDTH (GHz)
OPA855	Bipolar	7 V/V	0.98	0.8	8
OPA858	CMOS	7 V/V	2.5	0.8	5.5
OPA859	CMOS	1 V/V	3.3	0.8	0.9
LMH6629	Bipolar	10 V/V	0.69	5.7	4

6 Pin Configuration and Functions

DSG Package
8-Pin WSON With Exposed Thermal Pad
Top View



Not to scale

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
FB	1	I	Feedback connection to output of amplifier
IN–	3	I	Inverting input
IN+	4	I	Noninverting input
NC	2	—	Do not connect
OUT	6	O	Amplifier output
$\overline{PD}$	8	I	Power down connection. $\overline{PD}$ = logic low = power off mode; $\overline{PD}$ = logic high = normal operation.
VS–	5	—	Negative voltage supply
VS+	7	—	Positive voltage supply
Thermal pad		—	Connect the thermal pad to VS–

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7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_S	Total supply voltage (V_{S+} – $V_{S–}$)		5.5	V
V_{IN+}, $V_{IN–}$	Input voltage	($V_{S–}$) – 0.5	(V_{S+}) + 0.5	V
V_{ID}	Differential input voltage		1	V
V_{OUT}	Output voltage	($V_{S–}$) – 0.5	(V_{S+}) + 0.5	V
I_{IN}	Continuous input current		±10	mA
I_{OUT}	Continuous output current(2)		±100	mA
T_J	Junction temperature		150	°C
T_A	Operating free-air temperature	–40	125	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Long-term continuous output current for electromigration limits.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±1500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_S	Total supply voltage (V_{S+} – $V_{S–}$)	3.3	5	5.25	V
T_A	Operating free-air temperature	–40		125	°C

7.4 Thermal Information

THERMAL METRIC(1)		OPA855 DSG (WSON) 8 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	80.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	100	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	45	°C/W
ψ_{JT}	Junction-to-top characterization parameter	6.8	°C/W
ψ_{JB}	Junction-to-board characterization parameter	45.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	22.7	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

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7.5 Electrical Characteristics

at V_{S+} = 5 V, $V_{S–}$ = 0 V, G = 7 V/V, R_F = 453 Ω, input common-mode biased at midsupply, R_L = 200 Ω, output load is referenced to midsupply, and T_A = 25℃ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
AC PERFORMANCE						
SSBW	Small-signal bandwidth	V_{OUT} = 100 mV_{PP}		2.5		GHz
LSBW	Large-signal bandwidth	V_{OUT} = 2 V_{PP}		850		MHz
GBWP	Gain-bandwidth product			8		GHz
	Bandwdith for 0.1-dB flatness			200		MHz
SR	Slew rate (10%-90%)	V_{OUT} = 2-V step		2750		V/µs
t_r	Rise time	V_{OUT} = 100-mV step		0.17		ns
t_f	Fall time	V_{OUT} = 100-mV step		0.17		ns
	Settling time to 0.1%	V_{OUT} = 2-V step		2.3		ns
	Settling time to 0.001%	V_{OUT} = 2-V step		2600		ns
	Overshoot or undershoot	V_{OUT} = 2-V step		5%		
	Overdrive recovery	2x output overdrive		3		ns
HD2	Second-order harmonic distortion	f = 10 MHz, V_{OUT} = 2 V_{PP}		90		dBc
		f = 100 MHz, V_{OUT} = 2 V_{PP}		65		
HD3	Third-order harmonic distortion	f = 10 MHz, V_{OUT} = 2 V_{PP}		86		dBc
		f = 100 MHz, V_{OUT} = 2 V_{PP}		74		
e_n	Input-referred voltage noise	f = 1 MHz		0.98		nV/√Hz
e_i	Input-referred current noise	f = 1 MHz		2.5		pA/√Hz
z_O	Closed-loop output impedance	f = 1 MHz		0.15		Ω
DC PERFORMANCE						
A_{OL}	Open-loop voltage gain		70	76		dB
V_{OS}	Input offset voltage	T_A = 25°C	–1.5	±0.2	1.5	mV
$\Delta V_{OS}/\Delta T$	Input offset voltage drift	T_A = –40°C to 125°C		0.5		µV/°C
I_B	Input bias current (1)	T_A = 25°C	–18.5	–12	–5	µA
$\Delta I_B/\Delta T$	Input bias current drift	T_A = –40°C to +125°C		–0.08		µA/°C
I_{BOS}	Input offset current	T_A = 25°C	–1	±0.1	1	µA
$\Delta I_{BOS}/\Delta T$	Input offset current drift	T_A = –40°C to +125°C		1		nA/°C
CMRR	Common-mode rejection ratio	V_{CM} = ±0.5 V referred to midsupply	90	100		dB
INPUT						
	Common-mode input resistance			2.3		MΩ
C_{CM}	Common-mode input capacitance			0.6		pF
	Differential input resistance			5		kΩ
C_{DIFF}	Differential input capacitance			0.2		pF
V_{IH}	Common-mode input range (high)	CMRR > 80 dB, V_{S+} = 3.3 V	2.7	2.9		V
V_{IL}	Common-mode input range (low)	CMRR > 80 dB, V_{S+} = 3.3 V		1.1	1.3	V
V_{IH}	Common-mode input range (high)	CMRR > 80 dB	4.4	4.6		V
V_{IH}	Common-mode input range (high)	T_A = –40°C to +125 °C, CMRR > 80 dB		4.3		V
V_{IL}	Common-mode input range (low)	CMRR > 80 dB		1.1	1.3	V
V_{IL}	Common-mode input range (low)	T_A = –40°C to +125°C, CMRR > 80 dB		1.3		V

(1) Current flowing into the input pin is considered negative

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Electrical Characteristics (continued)

at V_{S+} = 5 V, $V_{S–}$ = 0 V, G = 7 V/V, R_F = 453 Ω, input common-mode biased at midsupply, R_L = 200 Ω, output load is referenced to midsupply, and T_A = 25°C (unless otherwise noted)

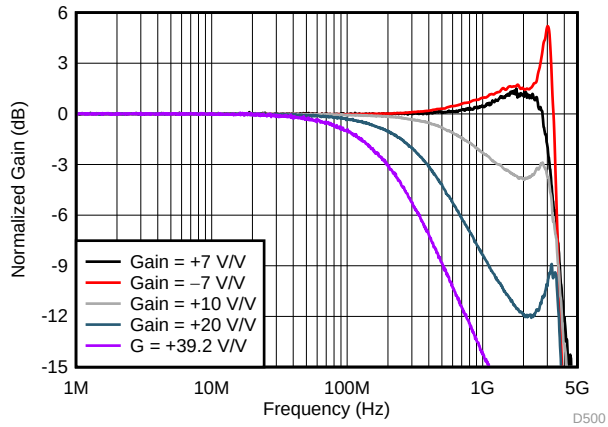
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT						
V_{OH}	Output voltage (high)(2)	T_A = 25°C, V_{S+} = 3.3 V	2.35	2.4		V
V_{OH}	Output voltage (high)(2)	T_A = 25°C	3.95	4.1		V
		T_A = –40°C to +125°C		4		
V_{OL}	Output voltage (low)(2)	T_A = 25°C, V_{S+} = 3.3 V		1.05	1.15	V
V_{OL}	Output voltage (low)(2)	T_A = 25°C		1.05	1.15	V
		T_A = –40°C to +125°C		1.1		
I_{O_LIN}	Linear output drive (sink and source)	R_L = 10 Ω, A_{OL} > 60 dB	65	80		mA
		T_A = –40°C to +125°C, R_L = 10 Ω, A_{OL} > 60 dB		70		
I_{SC}	Output short-circuit current		85	105		mA
POWER SUPPLY						
I_Q	Quiescent current		16	17.8	19.5	mA
		T_A = –40°C		16.7		
		T_A = 125°C		19.5		
PSRR+	Positive power-supply rejection ratio		80	86		dB
PSRR–	Negative power-supply rejection ratio		70	80		
POWER DOWN						
	Disable voltage threshold	Amplifier OFF below this voltage	0.65	1		V
	Enable voltage threshold	Amplifier ON below this voltage		1.5	1.8	V
	Power-down quiescent current			70	140	µA
	$\overline{PD}$ bias current			70	140	µA
	Turnon time delay	Time to V_{OUT} = 90% of final value		15		ns
	Turnoff time delay			120		ns

(2) Amplifier output saturated

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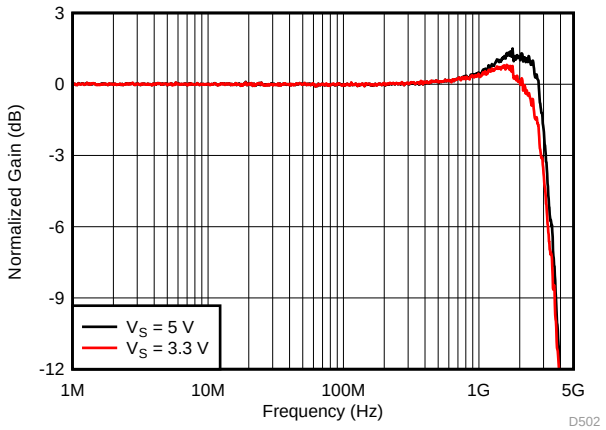
7.6 Typical Characteristics

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)



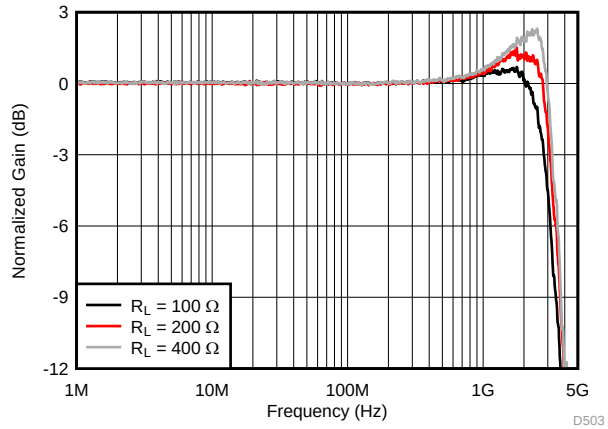
V_{OUT} = 100 mV_{PP}; See Parameter Measurement Information for circuit configuration

Figure 1. Small-Signal Frequency Response vs Gain



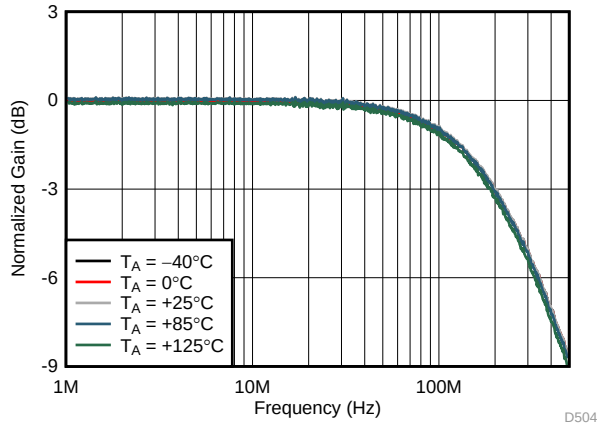
V_{OUT} = 100 mV_{PP}

Figure 2. Small-Signal Frequency Response vs Supply Voltage



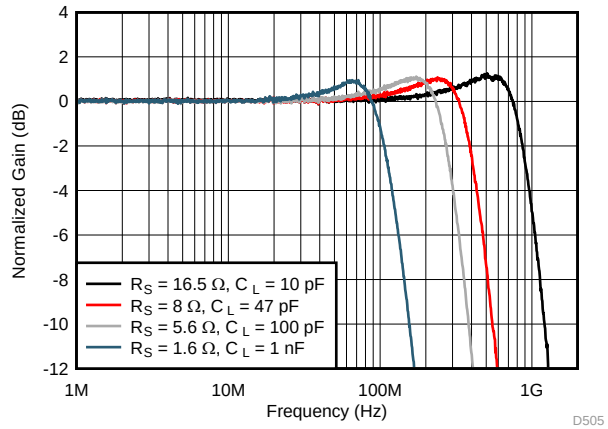
V_{OUT} = 100 mV_{PP}

Figure 3. Small-Signal Frequency Response vs Output Load



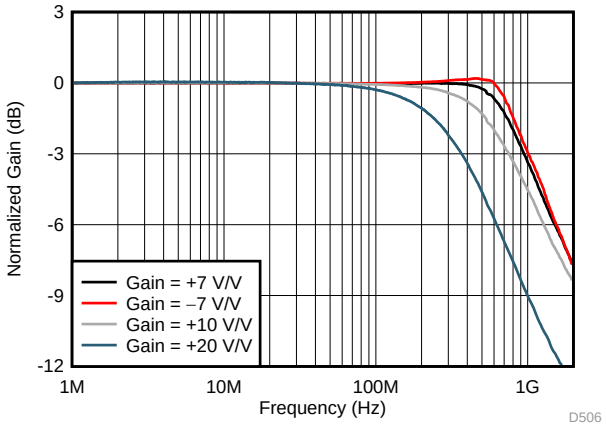
Gain = 39.2 V/V, R_F = 953 Ω V_{OUT} = 100 mV_{PP}

Figure 4. Small-Signal Frequency Response vs Ambient Temperature



V_{OUT} = 100 mV_{PP} ; See Figure 45 for circuit configuration

Figure 5. Small-Signal Frequency Response vs Capacitive Load



V_{OUT} = 2 V_{PP}

Figure 6. Large-Signal Frequency Response vs Gain

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Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)

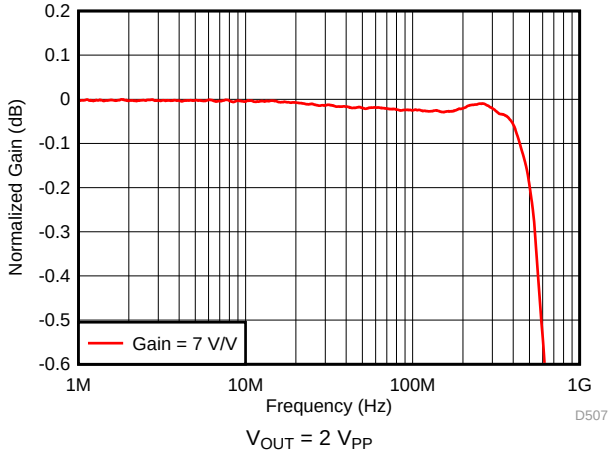


Figure 7. Large-Signal Response for 0.1-dB Gain Flatness

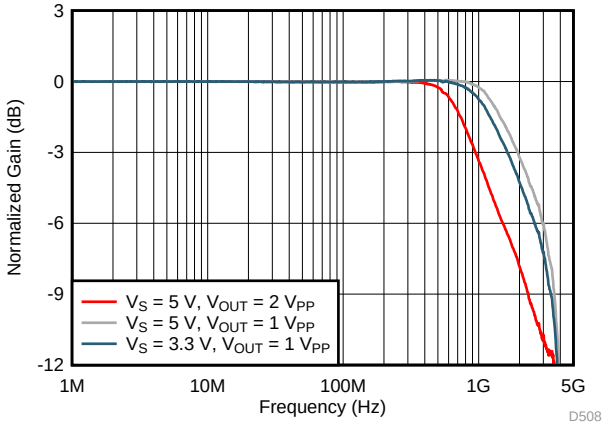


Figure 8. Large-Signal Frequency Response vs Voltage Supply

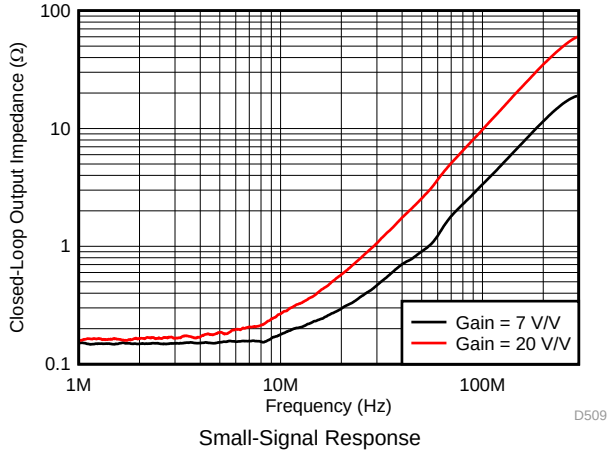


Figure 9. Closed-Loop Output Impedance vs Frequency

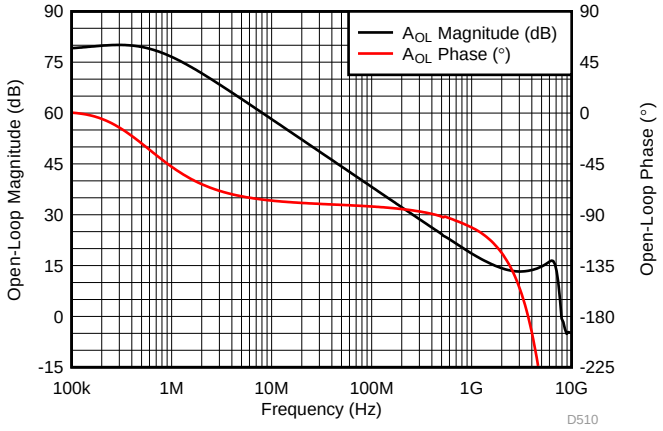


Figure 10. Open-Loop Magnitude and Phase vs Frequency

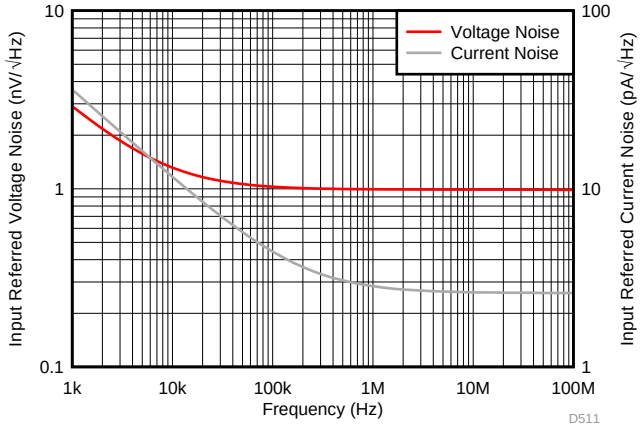


Figure 11. Voltage and Current Noise Density vs Frequency

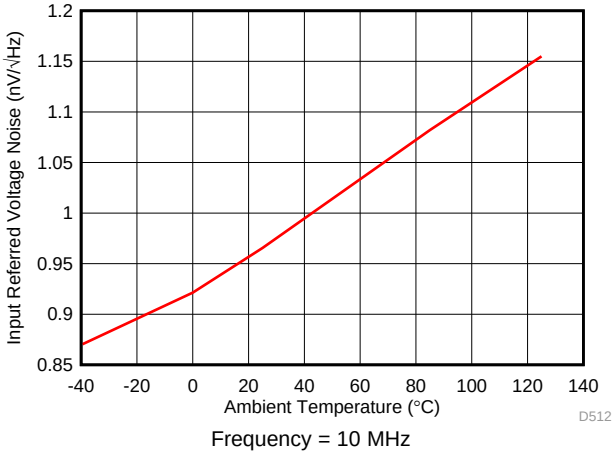


Figure 12. Voltage Noise Density vs Ambient Temperature

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Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)

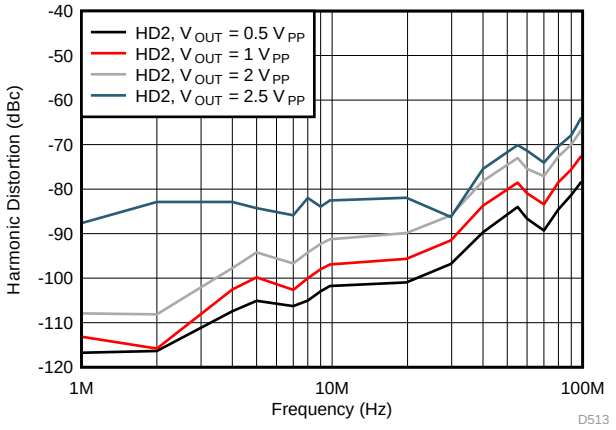


Figure 13. Harmonic Distortion (HD2) vs Output Swing

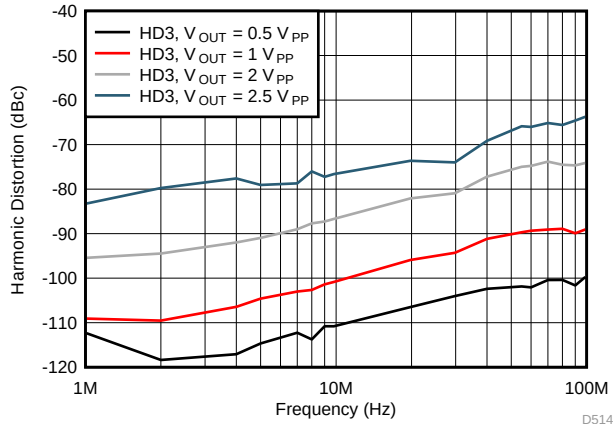


Figure 14. Harmonic Distortion (HD3) vs Output Swing

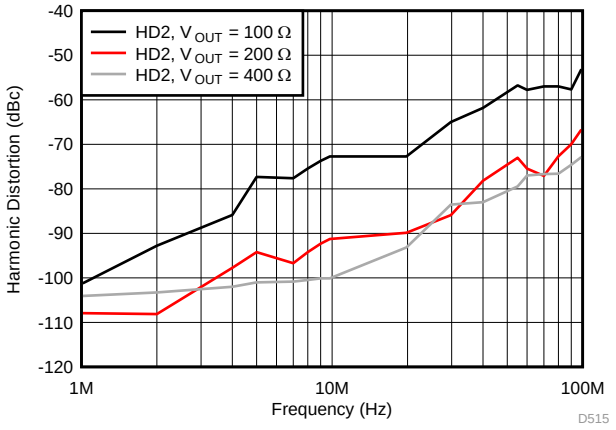


Figure 15. Harmonic Distortion (HD2) vs Output Load

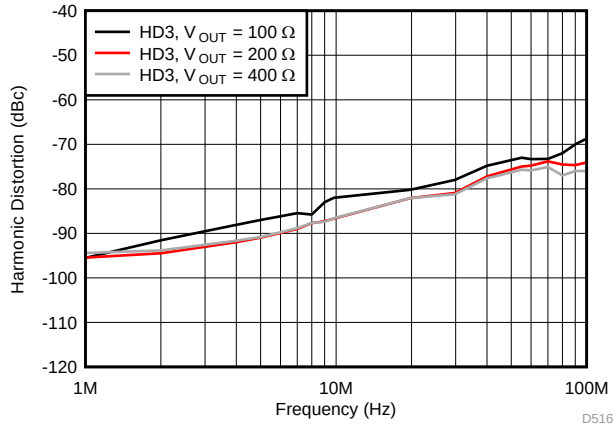


Figure 16. Harmonic Distortion (HD3) vs Output Load

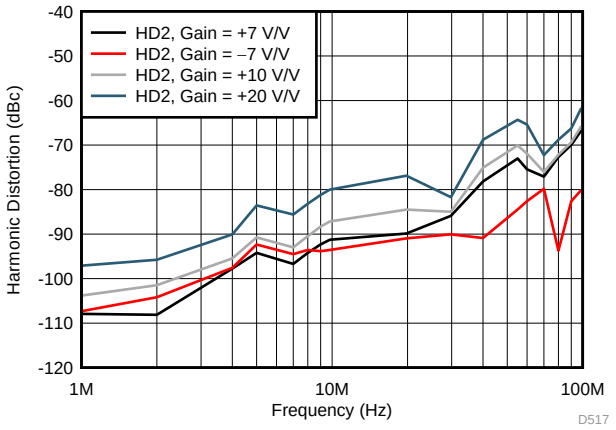


Figure 17. Harmonic Distortion (HD2) vs Gain

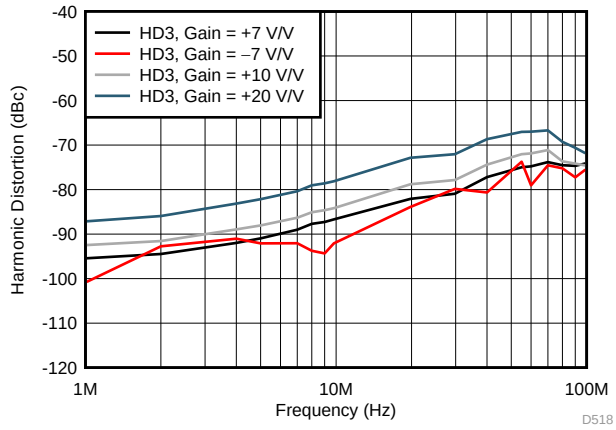
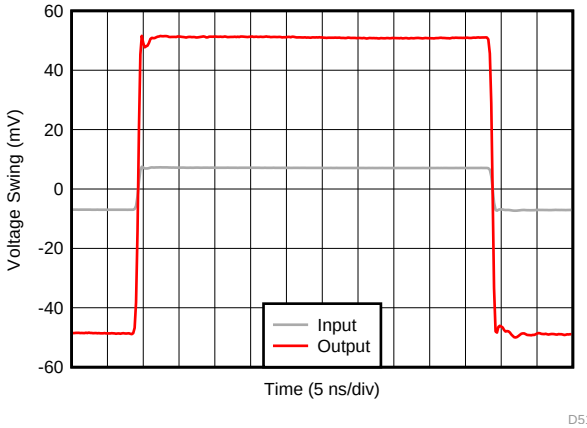


Figure 18. Harmonic Distortion (HD3) vs Gain

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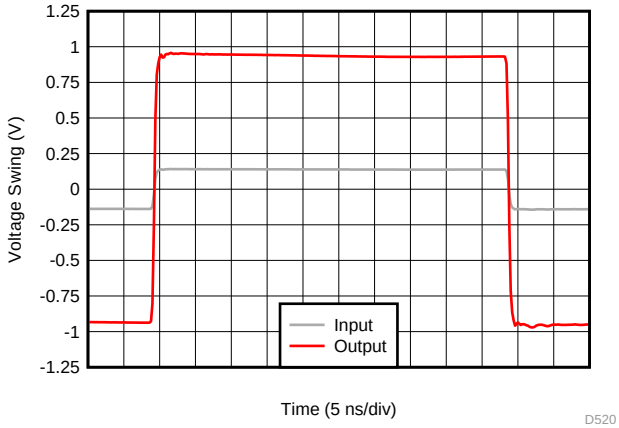
Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)



Average Rise and Fall Time (10% - 90%) = 300 ps
Rise and fall time limited by test equipment

Figure 19. Small-Signal Transient Response



Average Rise and Fall Time (10% - 90%) = 569 ps

Figure 20. Large-Signal Transient Response

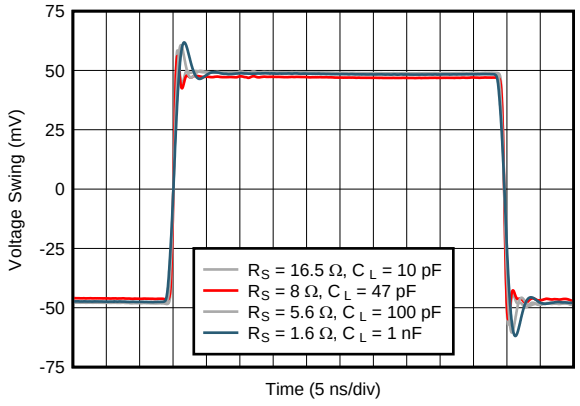
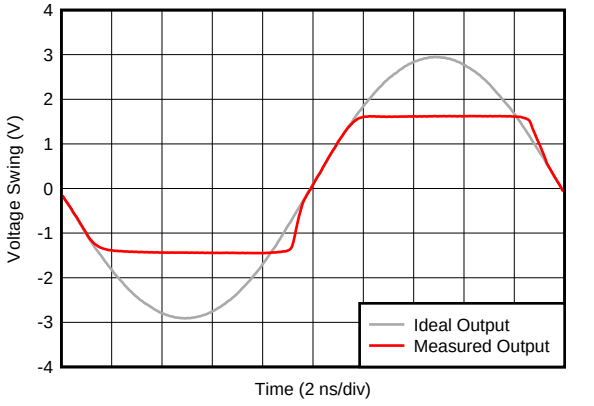


Figure 21. Small-Signal Transient Response vs Capacitive Load



2x Output Overdrive

Figure 22. Output Overload Response

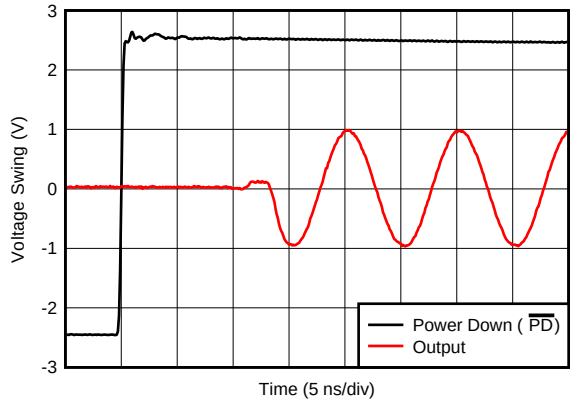


Figure 23. Turnon Transient Response

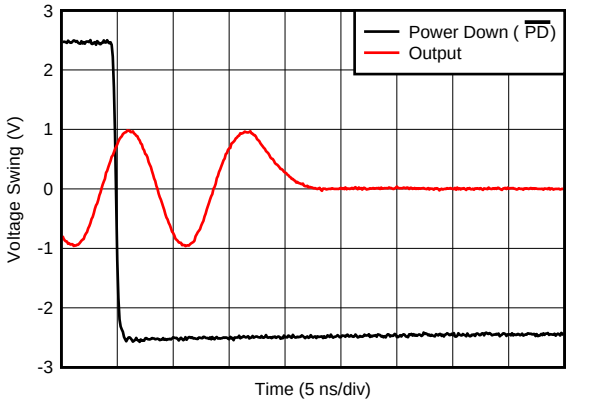


Figure 24. Turnoff Transient Response

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Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)

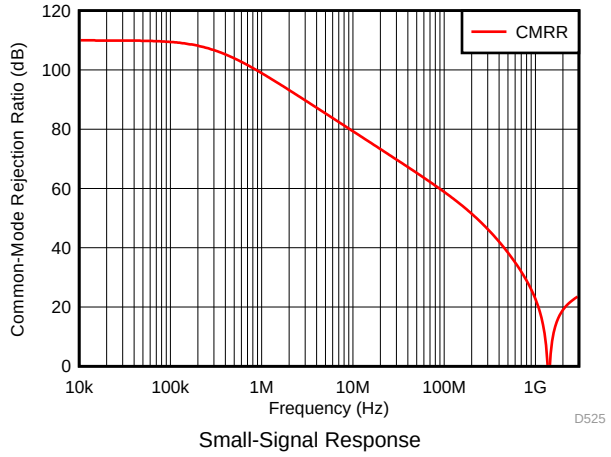


Figure 25. Common-Mode Rejection Ratio vs Frequency

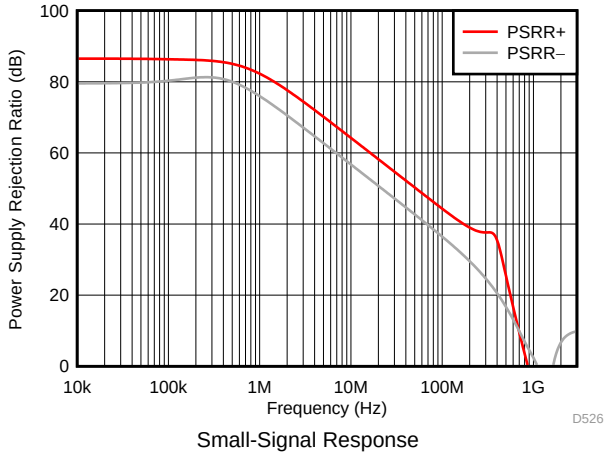


Figure 26. Power Supply Rejection Ratio vs Frequency

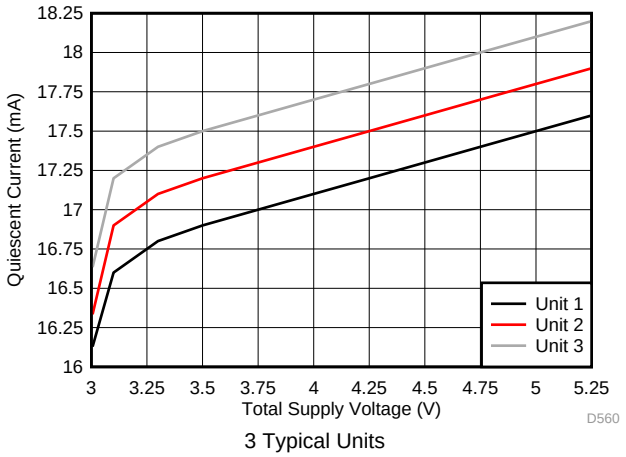


Figure 27. Quiescent Current vs Supply Voltage

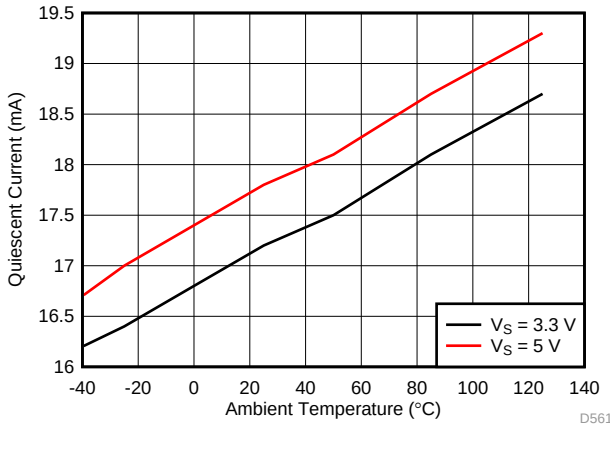


Figure 28. Quiescent Current vs Ambient Temperature

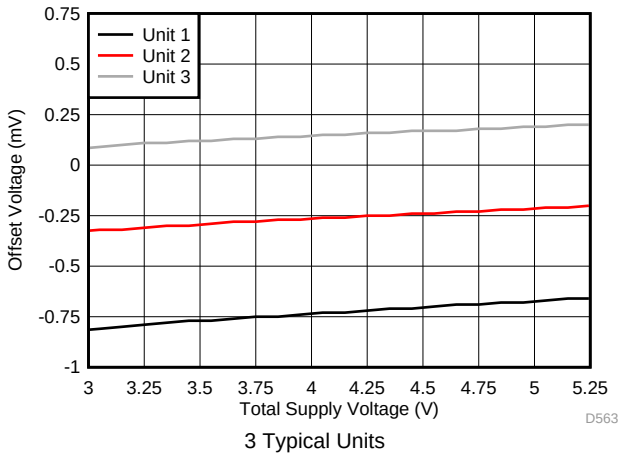


Figure 29. Offset Voltage vs Supply Voltage

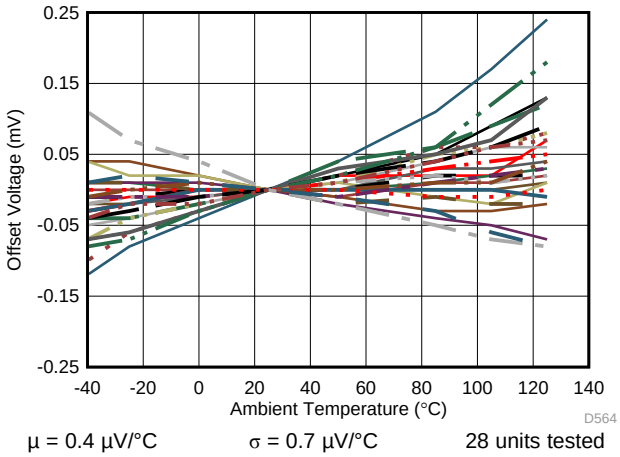


Figure 30. Offset Voltage vs Ambient Temperature

Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)

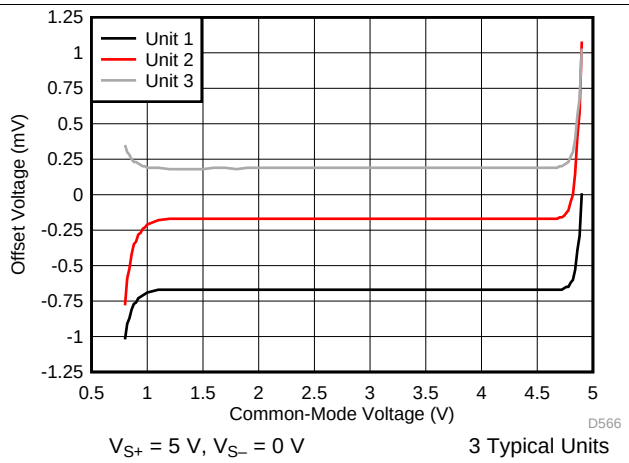


Figure 31. Offset Voltage vs Input Common-Mode Voltage

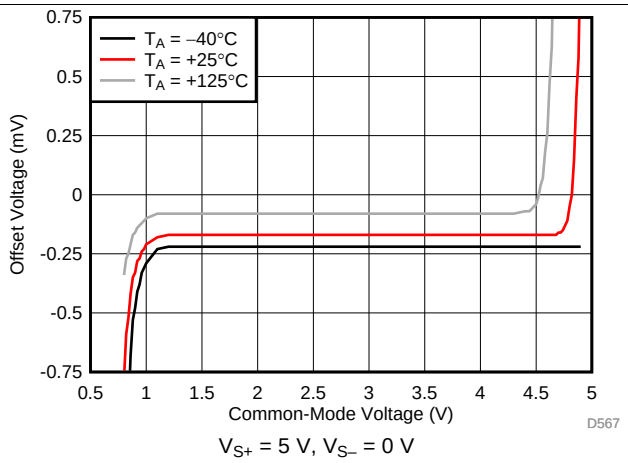


Figure 32. Offset Voltage vs Input Common-Mode Voltage vs Ambient Temperature

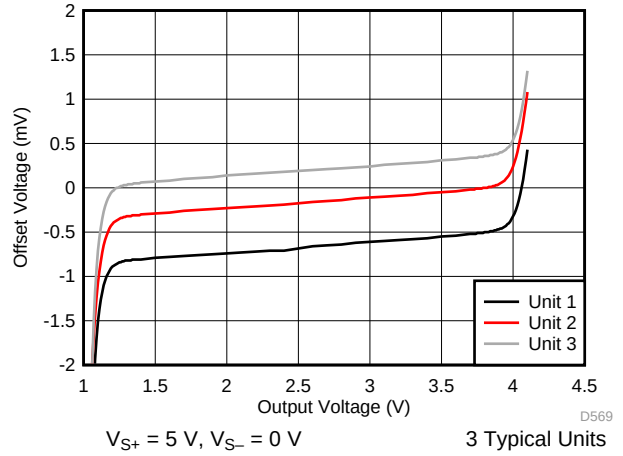


Figure 33. Offset Voltage vs Output Swing

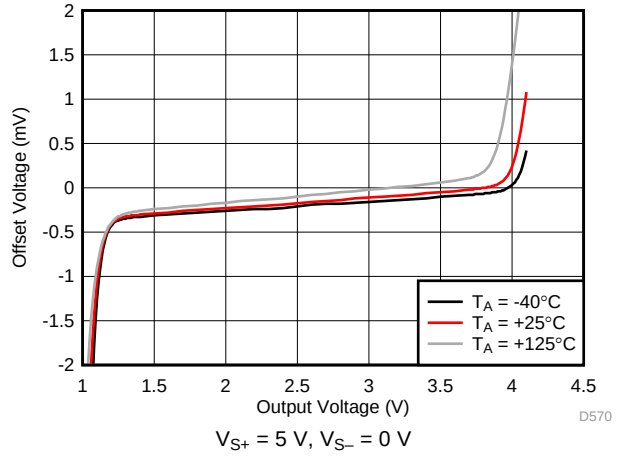


Figure 34. Offset Voltage vs Output Swing vs Ambient Temperature

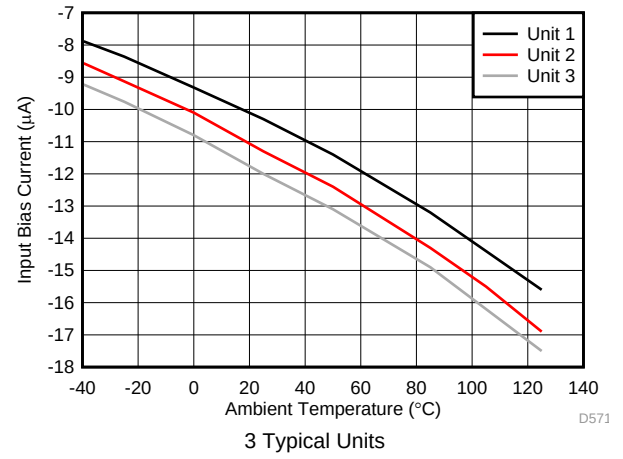


Figure 35. Input Bias Current vs Ambient Temperature

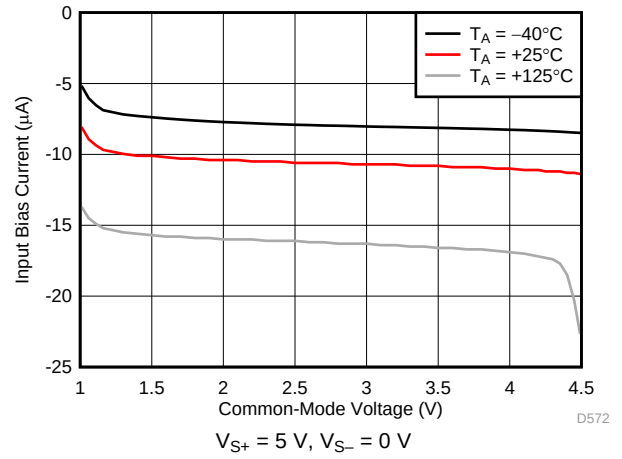
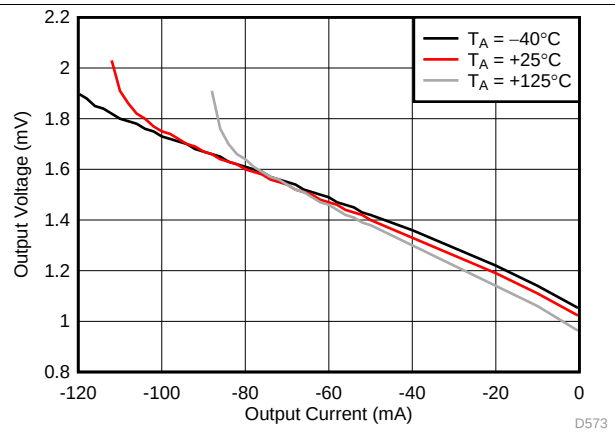


Figure 36. Input Bias Current vs Input Common-Mode Voltage vs Ambient Temperature

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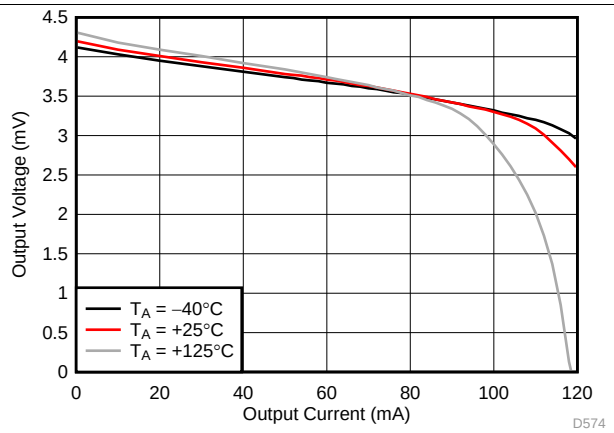
Typical Characteristics (continued)

at T_A = 25°C, V_{S+} = 2.5 V, $V_{S–}$ = –2.5 V, V_{IN+} = 0 V, R_F = 453 Ω, Gain = 7 V/V, R_L = 200 Ω, and output load referenced to midsupply (unless otherwise noted)



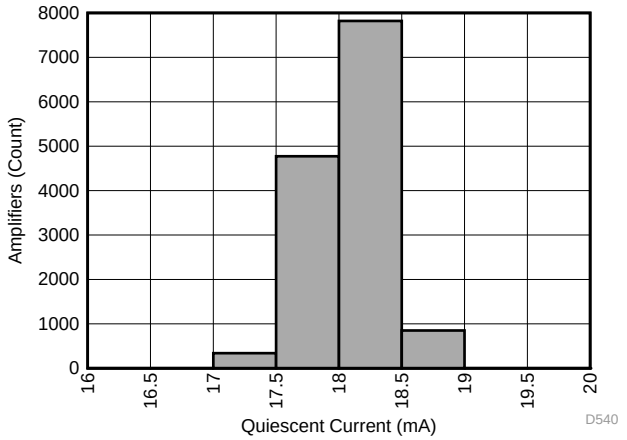
V_{S+} = 5 V, $V_{S–}$ = 0 V

Figure 37. Output Swing vs Sinking Current



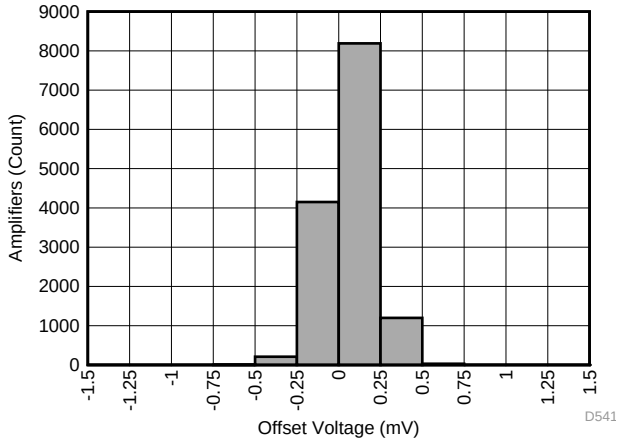
V_{S+} = 5 V, $V_{S–}$ = 0 V

Figure 38. Output Swing vs Sourcing Current



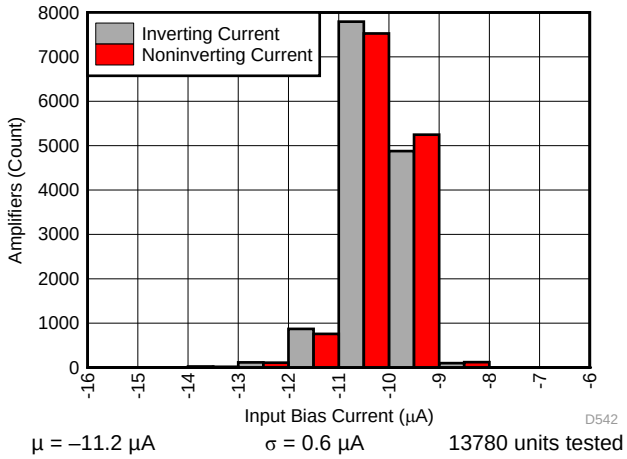
μ = 17.6 mA σ = 0.3 mA 13780 units tested

Figure 39. Quiescent Current Distribution



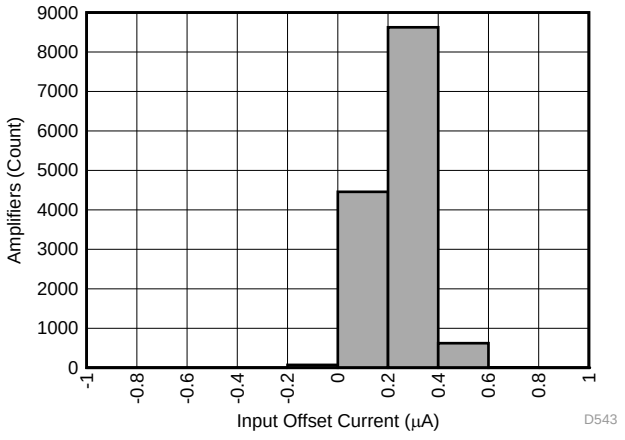
μ = –0.2 mV σ = 0.15 mV 13780 units tested

Figure 40. Offset Voltage Distribution



μ = –11.2 μA σ = 0.6 μA 13780 units tested

Figure 41. Input Bias Current Distribution



μ = 0.04 μA σ = 0.1 μA 13780 units tested

Figure 42. Input Offset Current Distribution

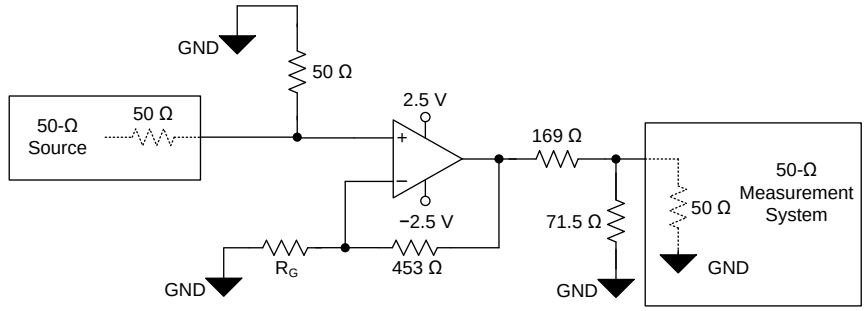
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8 Parameter Measurement Information

8.1 Parameter Measurement Information

The various test setup configurations for the OPA855 are shown in Figure 43, Figure 44, and Figure 45. When configuring the OPA855 in a gain of +39.2 V/V, feedback resistor R_F was set to 953 Ω.

Figure 1 shows 5-dB of peaking with the amplifier in an inverting configuration of –7 V/V with the amplifier configured as shown in Figure 44. The 50-Ω matched termination of this circuit configuration results in the amplifier being configured in a noise gain of 5.3 V/V, which is lower than the recommended +7 V/V.



R_G values depend on gain configuration

Figure 43. Noninverting Configuration

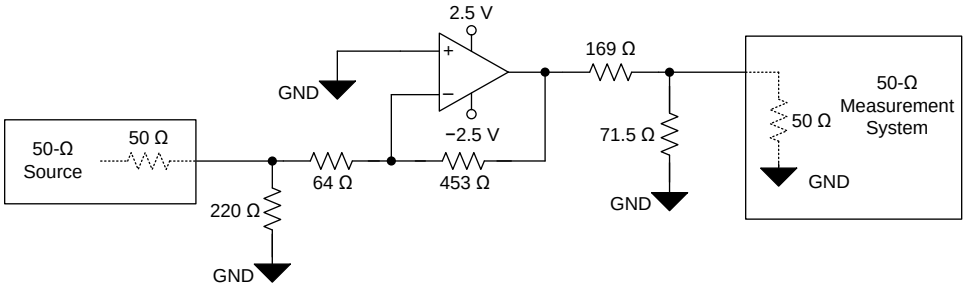


Figure 44. Inverting Configuration (Gain = –7 V/V)

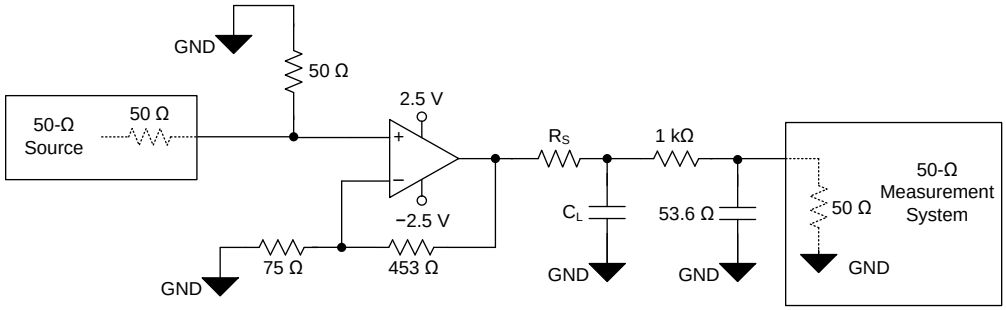


Figure 45. Capacitive Load Driver Configuration

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9 Detailed Description

9.1 Overview

The ultra-wide, 8-GHz gain bandwidth product (GBWP) of the OPA855, combined with the broadband voltage noise of 0.98 nV/√Hz, produces a viable amplifier for wideband transimpedance applications, high-speed data acquisition systems, and applications with weak signal inputs that require low-noise and high-gain front ends. The OPA855 combines multiple features to optimize dynamic performance. In addition to the wide, small-signal bandwidth, the OPA855 has 850 MHz of large-signal bandwidth (2 V_{PP}), and a slew rate of 2750 V/µs, making the device a viable option for high-speed pulsed applications.

The OPA855 is offered in a 2-mm × 2-mm, 8-pin WSON package that features a feedback (FB) pin for a simple feedback network connection between the amplifiers output and inverting input. Excess capacitance on an amplifiers input pin can reduce phase margin causing instability. This problem is exacerbated in the case of very wideband amplifiers like the OPA855. To reduce the effects of stray capacitance on the input node, the OPA855 pinout features an isolation pin (NC) between the feedback and inverting input pins that increases the physical spacing between them thereby reducing parasitic coupling at high frequencies. The OPA855 also features a very low capacitance input stage with only 0.8-pF of total input capacitance.

9.2 Functional Block Diagram

The OPA855 is a classic, voltage feedback operational amplifier (op amp) with two high-impedance inputs and a low-impedance output. Standard application circuits are supported, like the two basic options shown in Figure 46 and Figure 47.The resistor on the noninverting pin is used for bias current cancellation to minimize the output offset voltage. In a noninverting configuration the additional resistors on the noninverting pin add noise to the system so if SNR is critical, the resistor can be eliminated. In an inverting configuration the noninverting node is typically connected to a DC voltage, so the high-frequency noise contribution from the bias cancellation resistor can be bypassed by adding a large 1-µF capacitor in parallel to the resistor to shunt the noise. The DC operating point for each configuration is level-shifted by the reference voltage (V_{REF}), which is typically set to midsupply in single-supply operation. V_{REF} is typically connected to ground in split-supply applications.

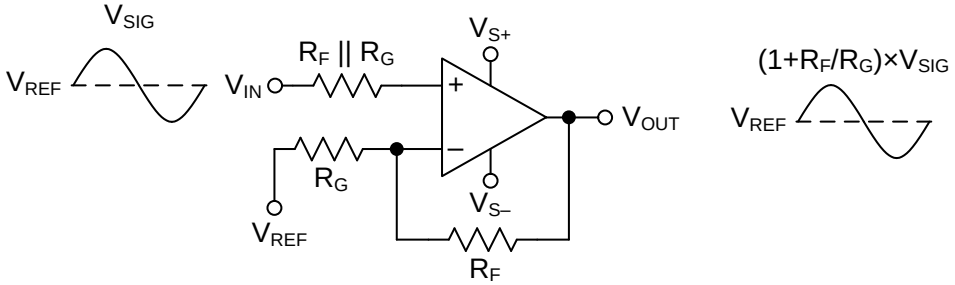


Figure 46. Noninverting Amplifier

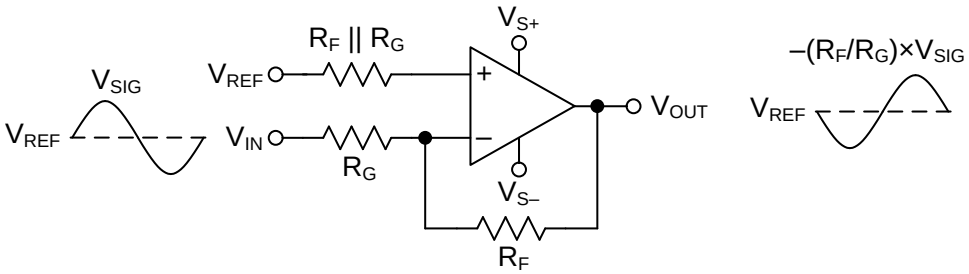


Figure 47. Inverting Amplifier

9.3 Feature Description

9.3.1 Input and ESD Protection

The OPA855 is fabricated on a low-voltage, high-speed, BiCMOS process. The internal, junction breakdown voltages are low for these small geometry devices, and as a result, all device pins are protected with internal ESD protection diodes to the power supplies as Figure 48 shows. There are two antiparallel diodes between the inputs of the amplifier that clamp the inputs during an overrange or fault condition.

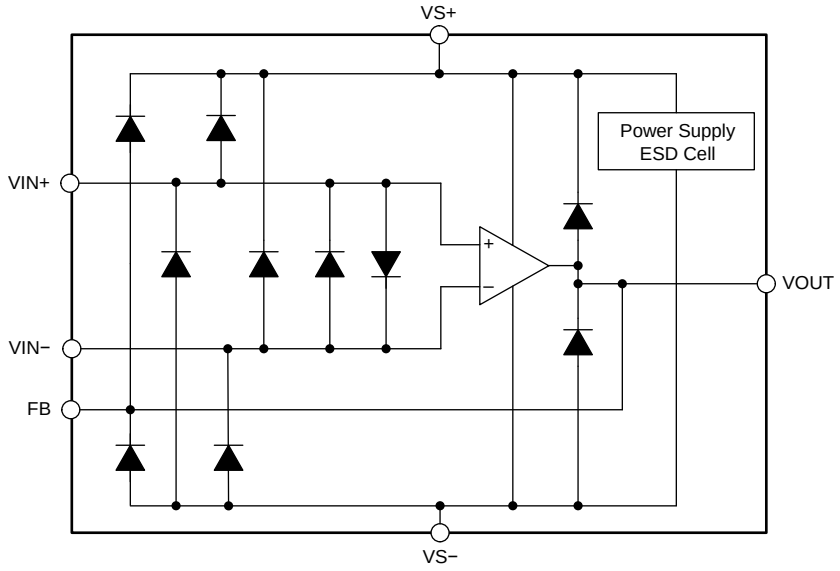


Figure 48. Internal ESD Structure

9.3.2 Feedback Pin

The OPA855 pin layout is optimized to minimize parasitic inductance and capacitance, which is critical in high-speed analog design. The FB pin (pin 1) is internally connected to the output of the amplifier. The FB pin is separated from the inverting input of the amplifier (pin 3) by a no connect (NC) pin (pin 2). The NC pin must be left floating. There are two advantages to this pin layout:

1. A feedback resistor (R_F) can connect between the FB and IN– pin on the same side of the package (see Figure 49) rather than going around the package.
2. The isolation created by the NC pin minimizes the capacitive coupling between the FB and IN– pins by increasing the physical separation between the pins.

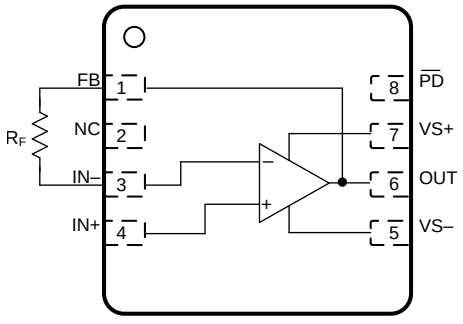


Figure 49. R_F Connection Between FB and IN– Pins

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Feature Description (continued)

9.3.3 Wide Gain-Bandwidth Product

Figure 10 shows the open-loop magnitude and phase response of the OPA855. Calculate the gain bandwidth product of any op amp by determining the frequency at which the A_{OL} is 40 dB and multiplying that frequency by a factor of 100. The open-loop response shows the OPA855 to have approximately 62° of phase-margin in a noise gain of 7 V/V. The second pole in the A_{OL} response occurs before the magnitude crosses 0 dB, and the resultant phase margin is less than 0°. This indicates instability at a gain of 0 dB (1 V/V). Amplifiers that are not unity-gain stable are known as decompensated amplifiers. Decompensated amplifiers typically have higher gain-bandwidth product, higher slew rate, and lower voltage noise, compared to a unity-gain stable amplifier with the same amount of quiescent power consumption.

Figure 50 shows the open-loop magnitude (A_{OL}) of the OPA855 as a function of temperature. The results show approximately 5° of phase-margin variation over the entire temperature range in a noise gain of 7 V/V. Semiconductor process variation is the naturally occurring variation in the attributes of a transistor (Early-voltage, β, channel-length and width) and other passive elements (resistors and capacitors) when fabricated into an integrated circuit. The process variation can occur across devices on a single wafer, or, across devices over multiple wafer lots over time. Typically, the variation across a single wafer is tightly controlled. Figure 51 shows the A_{OL} magnitude of the OPA855 as a function of process variation over time. The results show the A_{OL} curve for the nominal process corner and the variation one standard deviation from the nominal. The simulated results show less than 2° of phase-margin difference within a standard deviation of process variation in a noise gain of 7 V/V.

One of the primary applications for the OPA855 is as a high-speed transimpedance amplifier (TIA). The low-frequency noise gain of a TIA is 0 dB (1 V/V). At high frequencies the ratio of the total input capacitance and the feedback capacitance set the noise gain. To maximize the TIA closed-loop bandwidth, the feedback capacitance is typically smaller than the input capacitance, which implies that the high-frequency noise gain is greater than 0 dB. As a result, op amps configured as TIAs are not required to be unity-gain stable, which makes a decompensated amplifier a viable option for a TIA. *What You Need To Know About Transimpedance Amplifiers – Part 1* and *What You Need To Know About Transimpedance Amplifiers – Part 2* describe transimpedance amplifier compensation in greater detail.

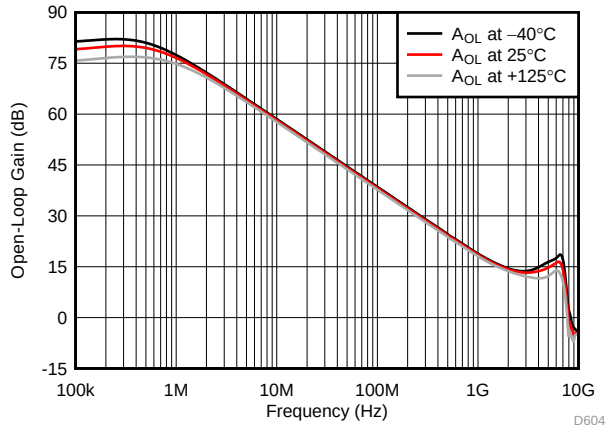


Figure 50. Open-Loop Gain vs Temperature

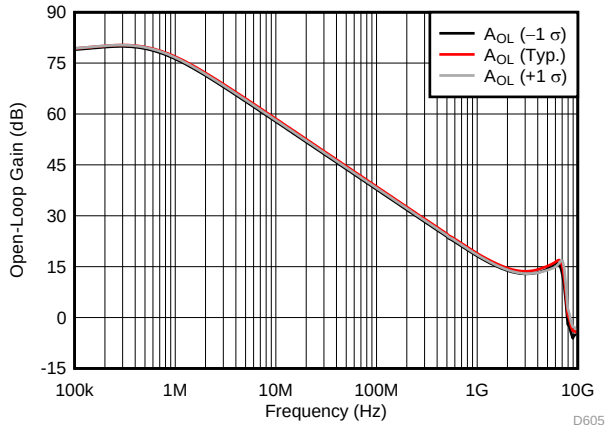


Figure 51. Open-Loop Gain vs Process Variation

Feature Description (continued)

9.3.4 Slew Rate and Output Stage

In addition to wide bandwidth, the OPA855 features a high slew rate of 2750 V/µs. The slew rate is a critical parameter in high-speed pulse applications with narrow sub-10-ns pulses, such as optical time-domain reflectometry (OTDR) and LIDAR. The high slew rate of the OPA855 implies that the device accurately reproduces a 2-V, sub-ns pulse edge, as seen in Figure 20. The wide bandwidth and slew rate of the OPA855 make it an excellent amplifier for high-speed signal-chain front ends.

Figure 52 shows the open-loop output impedance of the OPA855 as a function of frequency. To achieve high slew rates and low output impedance across frequency, the output swing of the OPA855 is limited to approximately 3 V. The OPA855 is typically used in conjunction with high-speed pipeline ADCs and flash ADCs that have limited input ranges. Therefore, the OPA855 output swing range coupled with the class-leading voltage noise specification maximizes the overall dynamic range of the signal chain.

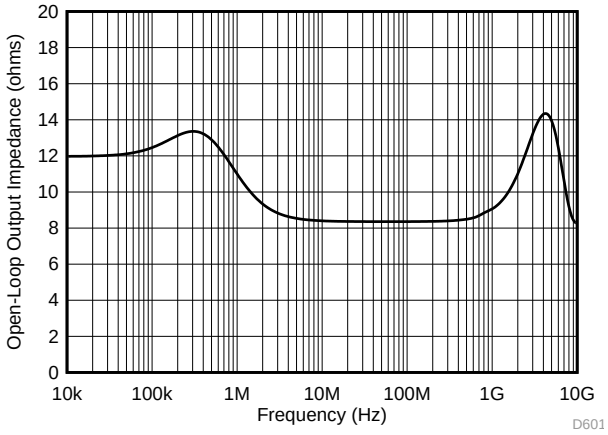


Figure 52. Open-Loop Output Impedance (Z_{OL}) vs Frequency

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9.4 Device Functional Modes

9.4.1 Split-Supply and Single-Supply Operation

The OPA855 can be configured with single-sided supplies or split-supplies as shown in Figure 58. Split-supply operation using balanced supplies with the input common-mode set to ground eases lab testing because most signal generators, network analyzers, spectrum analyzers, and other lab equipment typically reference inputs and outputs to ground. Split-supply operation is preferred in systems where the signals swing around ground. However, the system requires two supply rails. In split-supply operation, the thermal pad must be connected to the negative supply.

Newer systems use a single power supply to improve efficiency and reduce the cost of the extra power supply. The OPA855 can be used with a single positive supply (negative supply at ground) with no change in performance if the input common-mode and output swing are biased within the linear operation of the device. In single-supply operation, level shift the dc input and output reference voltages by half the difference between the power supply rails. This configuration maintains the input common-mode and output load reference at midsupply. To eliminate gain errors, the source driving the reference input common-mode voltage must have low output impedance across the frequency range of interest . In this case, the thermal pad must be connected to ground.

9.4.2 Power-Down Mode

The OPA855 features a power-down mode to reduce the quiescent current to conserve power. Figure 23 and Figure 24 show the transient response of the OPA855 as the $\overline{PD}$ pin toggles between the disabled and enabled states.

The $\overline{PD}$ disable and enable threshold voltages are with reference to the negative supply. If the amplifier is configured with the positive supply at 3.3 V and the negative supply at ground, then the disable and enable threshold voltages are 0.65 V and 1.8 V, respectively. If the amplifier is configured with ±1.65-V supplies, then the disable and enable threshold voltages are at –1 V and 0.15 V, respectively. If the amplifier is configured with ±2.5-V supplies, then the threshold voltages are at –1.85 V and –0.7 V.

Figure 53 shows the switching behavior of a typical amplifier as the $\overline{PD}$ pin is swept down from the enabled state to the disabled state. Similarly, Figure 54 shows the switching behavior of a typical amplifier as the $\overline{PD}$ pin is swept up from the disabled state to the enabled state. The small difference in the switching thresholds between the down sweep and the up sweep is caused by the hysteresis designed into the amplifier to increase immunity to noise on the $\overline{PD}$ pin.

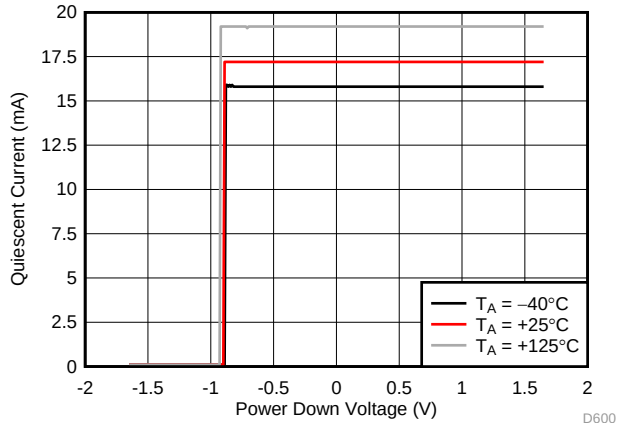


Figure 53. Switching Threshold ($\overline{PD}$ Pin Swept from High to Low)

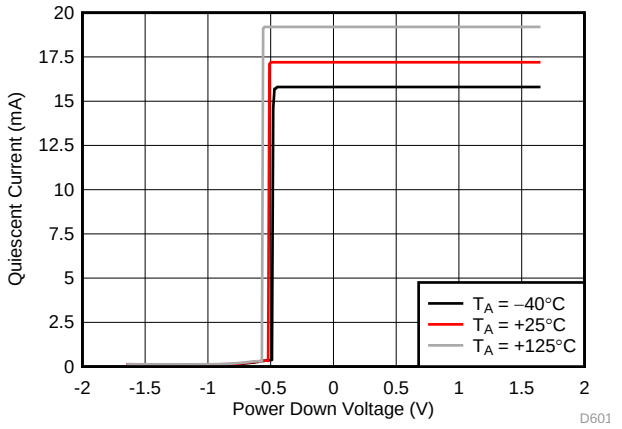


Figure 54. Switching Threshold ($\overline{PD}$ Pin Swept from Low to High)

Connecting the $\overline{PD}$ pin low disables the amplifier and places the output in a high-impedance state. When the amplifier is configured as a noninverting amplifier, the feedback (R_F) and gain (R_G) resistor network form a parallel load to the output of the amplifier. To protect the input stage of the amplifier, the OPA855 uses internal, back-to-back protection diodes between the inverting and noninverting input pins as Figure 48 shows. In the power-down state, if the differential voltage between the input pins of the amplifier exceeds a diode voltage drop, an additional low-impedance path is created between the noninverting input pin and the output pin.

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10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

The OPA855 offers very high-bandwidth, high slew-rate, low noise, and better than –60 dBc of distortion performance at frequencies of up to 100 MHz. These features make this device an excellent low-noise amplifier in high-speed data acquisition systems.

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10.2 Typical Application

Figure 55 shows the OPA855 configured as a transimpedance amplifier (U1) in a wide-bandwidth, optical front-end system. A second amplifier, the OPA859, configured as a unity-gain buffer (U2) sets a dc offset voltage to the THS4520. The THS4520 is used to convert the single-ended transimpedance output of the OPA855 into a differential output signal. The THS4520 drives the input of the ADS54J64, 14-bit, 1-GSPS analog-to-digital converter (ADC) that digitizes the analog signal.

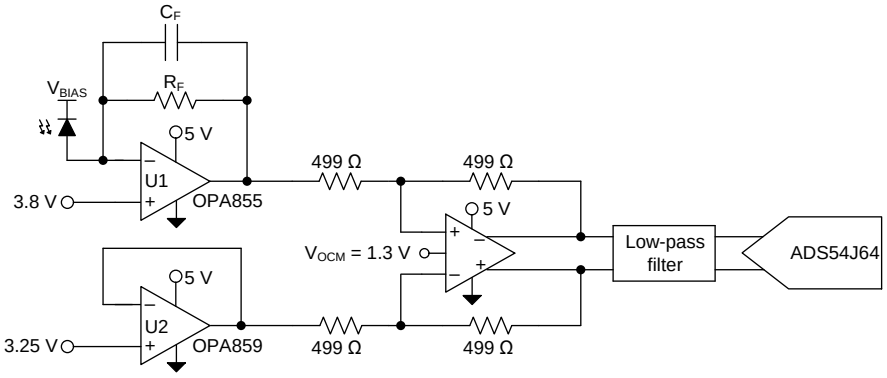


Figure 55. OPA855 as a TIA in an Optical Front-End System

10.2.1 Design Requirements

The objective is to design a low noise, wideband optical front-end system using the OPA855 as a transimpedance amplifier. The design requirements are:

- Amplifier supply voltage: 5 V
- TIA common-mode voltage: 3.8 V
- THS4520 gain: 1 V/V
- ADC input common-mode voltage: 1.3 V
- ADC analog differential input range: 1.1 V_{PP}

10.2.2 Detailed Design Procedure

The closed-loop bandwidth of a transimpedance amplifier is a function of the following:

1. The total input capacitance (C_{IN}). This total includes the photodiode capacitance, the input capacitance of the amplifier (common-mode and differential capacitance) and any stray capacitance from the PCB.
2. The op amp gain bandwidth product (GBWP).
3. The transimpedance gain (R_F).

Figure 55 shows the OPA855 configured as a TIA, with the avalanche photodiode (APD) reverse biased so that the APD cathode is tied to a large positive bias voltage. In this configuration, the APD sources current into the op amp feedback loop so that the output swings in a negative direction relative to the input common-mode voltage. To maximize the output swing in the negative direction, the OPA855 common-mode voltage is set close to the positive limit; only 1.2 V from the positive supply rail. The feedback resistance (R_F) and the input capacitance (C_{IN}) form a zero in the noise gain that results in instability if left unchecked. To counteract the effect of the zero, a pole is inserted into the noise gain transfer function by adding the feedback capacitor (C_F).

The *Transimpedance Considerations for High-Speed Amplifiers Application Report* discusses theories and equations that show how to compensate a transimpedance amplifier for a particular transimpedance gain and input capacitance. The bandwidth and compensation equations from the application report are available in an Excel™ calculator. *What You Need To Know About Transimpedance Amplifiers – Part 1* provides a link to the calculator.

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Typical Application (continued)

The equations and calculators in the referenced application report and blog posts are used to model the bandwidth (f_{-3dB}) and noise (I_{RN}) performance of the OPA855 configured as a TIA. The resultant performance is shown in Figure 56 and Figure 57. The left-side Y-axis shows the closed-loop bandwidth performance, whereas the right side of the graph shows the integrated input-referred noise. The noise bandwidth to calculate I_{RN} for a fixed R_F and C_{PD} is set equal to the f_{-3dB} frequency. Figure 56 shows the amplifier performance as a function of photodiode capacitance (C_{PD}) for R_F = 6 kΩ and 12 kΩ. Increasing C_{PD} decreases the closed-loop bandwidth. To maximize bandwidth, make sure to reduce any stray parasitic capacitance from the PCB. The OPA855 is designed with 0.8 pF of total input capacitance to minimize the effect of stray capacitance on system performance. Figure 57 shows the amplifier performance as a function of R_F for C_{PD} = 1.5 pF and 2.5 pF. Increasing R_F results in lower bandwidth. To maximize the signal-to-noise ratio (SNR) in an optical front-end system, maximize the gain in the TIA stage. Increasing R_F by a factor of X increases the signal level by X, but only increases the resistor noise contribution by $\sqrt{X}$, thereby improving SNR. Since the OPA855 is a bipolar input amplifier, increasing the feedback resistance increases the voltage offset due to the bias current and also increases the total output noise due to increased noise contributions from the amplifiers current noise.

The OPA859 configured as a unity-gain buffer drives a dc offset voltage of 3.25 V into the lower half of the THS4520. To maximize the dynamic range of the ADC, the OPA855 and OPA859 drive a differential common-mode of 3.8 V and 3.25 V respectively into the THS4520. The dc offset voltage of the buffer amplifier can be derived using Equation 1.

$$V_{BUF_DC} = V_{TIA_CM} - \left(\frac{1}{2} \times \frac{V_{ADC_DIFF_IN}}{\left(\frac{R_F}{R_G} \right)} \right) \quad (1)$$

where

- V_{TIA_CM} is the common-mode voltage of the TIA (3.8 V)
- $V_{ADC_DIFF_IN}$ is the differential input voltage range of the ADC (1.1 V_{PP})
- R_F and R_G are the feedback resistance (499 Ω) and gain resistance (499 Ω) of the THS4520 differential amplifier

The low-pass filter between the THS4520 and the ADC54J64 minimizes high-frequency noise and maximizes SNR. The ADC54J64 has an internal buffer that isolates the output of the THS4520 from the ADC sampling-capacitor input, so a traditional charge bucket filter is not required.

10.2.3 Application Curves

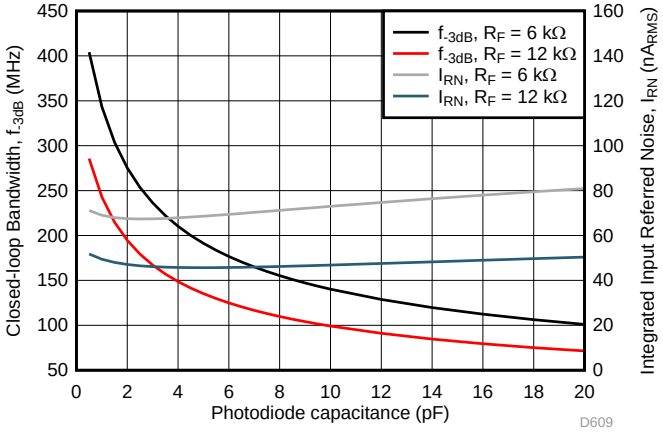


Figure 56. Bandwidth and Noise vs Photodiode Capacitance

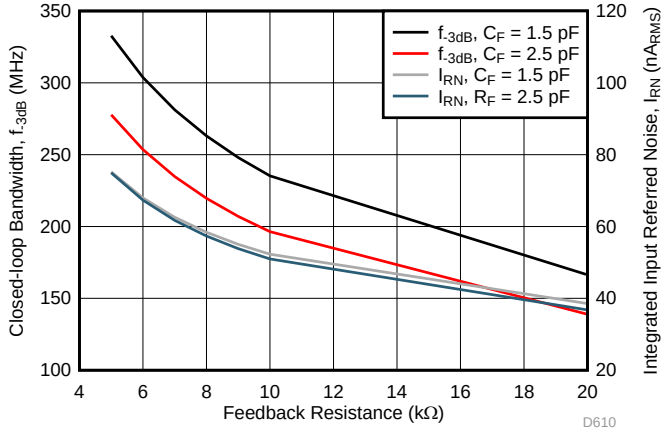


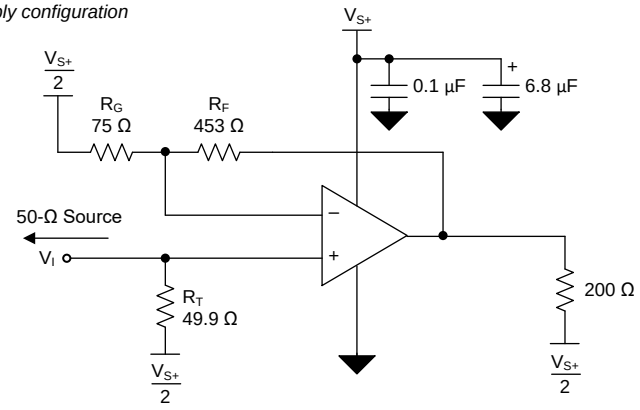
Figure 57. Bandwidth and Noise vs Feedback Resistance

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11 Power Supply Recommendations

The OPA855 operates on supplies from 3.3 V to 5.25 V. The OPA855 operates on single-sided supplies, split and balanced bipolar supplies, and unbalanced bipolar supplies. Because the OPA855 does not feature rail-to-rail inputs or outputs, the input common-mode and output swing ranges are limited at 3.3-V supplies.

a) Single supply configuration



b) Split supply configuration

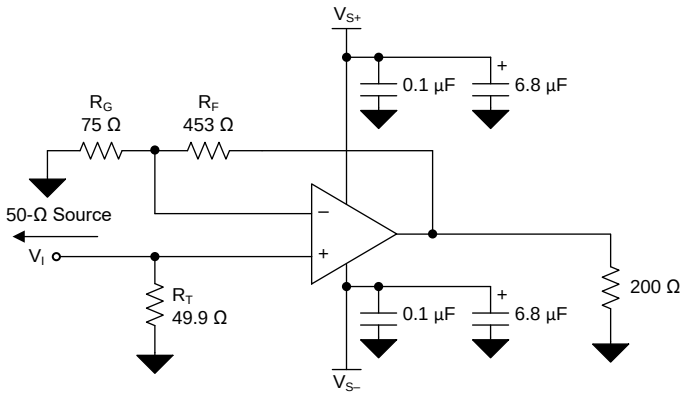


Figure 58. Split and Single Supply Circuit Configuration

12 Layout

12.1 Layout Guidelines

Achieving optimum performance with a high-frequency amplifier like the OPA855 requires careful attention to board layout parasitics and external component types. Recommendations that optimize performance include:

- **Minimize parasitic capacitance from the signal I/O pins to ac ground.** Parasitic capacitance on the output and inverting input pins can cause instability. To reduce unwanted capacitance, cut out the power and ground traces under the signal input and output pins. Otherwise, ground and power planes must be unbroken elsewhere on the board. When configuring the amplifier as a TIA, if the required feedback capacitor is less than 0.15 pF, consider using two series resistors, each of half the value of a single resistor in the feedback loop to minimize the parasitic capacitance from the resistor.
- **Minimize the distance (less than 0.25") from the power-supply pins to high-frequency bypass capacitors.** Use high-quality, 100-pF to 0.1-µF, C0G and NPO-type decoupling capacitors with voltage ratings at least three times greater than the amplifiers maximum power supplies. This configuration makes sure that there is a low-impedance path to the amplifiers power-supply pins across the amplifiers gain bandwidth specification. At the device pins, do not allow the ground and power plane layout to be in close proximity to the signal I/O pins. Avoid narrow power and ground traces to minimize inductance between the pins and the decoupling capacitors. The power-supply connections must always be decoupled with these capacitors. Larger (2.2-µF to 6.8-µF) decoupling capacitors that are effective at lower frequency must be used on the supply pins. Place these decoupling capacitors further from the device. Share the decoupling capacitors among several devices in the same area of the printed circuit board (PCB).
- **Careful selection and placement of external components preserves the high-frequency performance of the OPA855.** Use low-reactance resistors. Surface-mount resistors work best and allow a tighter overall layout. Never use wirewound resistors in a high-frequency application. Because the output pin and inverting input pin are the most sensitive to parasitic capacitance, always position the feedback and series output resistor, if any, as close to the output pin as possible. Place other network components (such as noninverting input termination resistors) close to the package. Even with a low parasitic capacitance shunting the external resistors, high resistor values create significant time constants that can degrade performance. When configuring the OPA855 as a voltage amplifier, keep resistor values as low as possible and consistent with load driving considerations. Decreasing the resistor values keeps the resistor noise terms low and minimizes the effect of the parasitic capacitance. However, lower resistor values increase the dynamic power consumption because R_F and R_G become part of the output load network of the amplifier.

12.2 Layout Example

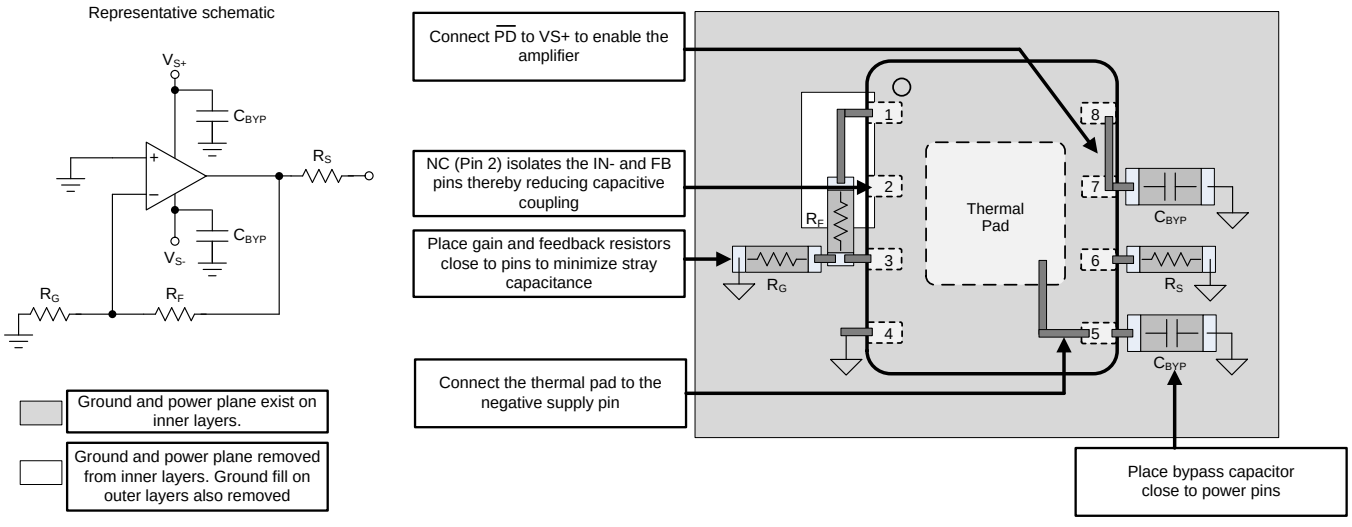


Figure 59. Layout Recommendation

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Layout Example (continued)

When configuring the OPA855 as a transimpedance amplifier additional care must be taken to minimize the inductance between the avalanche photodiode (APD) and the amplifier. Always place the photodiode on the same side of the PCB as the amplifier. Placing the amplifier and the APD on opposite sides of the PCB increases the parasitic effects due to via inductance. APD packaging can be quite large which often requires the APD to be placed further away from the amplifier than ideal. The added distance between the two device results in increased inductance between the APD and op amp feedback network as shown in Figure 60. The added inductance is detrimental to a decompensated amplifiers stability since it isolates the APD capacitance from the noise gain transfer function. The noise gain is given by Equation 2. The added PCB trace inductance between the feedback network increases the denominator in Equation 2 thereby reducing the noise gain and the phase margin. In cases where a leaded APD in a TO can is used inductance should be further minimized by cutting the leads of the TO can as short as possible.

The layout shown in Figure 60 can be improved by following some of the guidelines shown in Figure 61. The two key rules to follow are:

- Add an isolation resistor R_{ISO} as close as possible to the inverting input of the amplifier. Select the value of R_{ISO} to be between 10 Ω and 20 Ω. The resistor dampens the potential resonance caused by the trace inductance and the amplifiers internal capacitance.
- Close the loop between the feedback elements (R_F and C_F) and R_{ISO} as close to the APD pins as possible. This ensures a more balanced layout and reduces the inductive isolation between the APD and the feedback network.

$$\text{Noise Gain} = \left(1 + \frac{Z_F}{Z_{IN}}\right) \quad (2)$$

where

- Z_F is the total impedance of the feedback network.
- Z_{IN} is the total impedance of the input network.

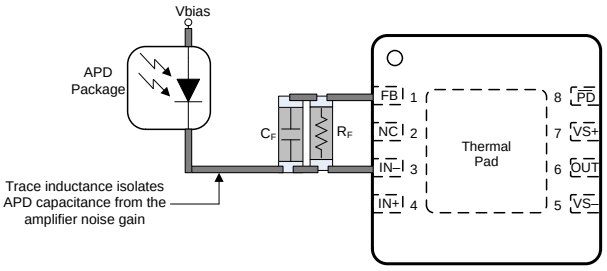


Figure 60. Non-Ideal TIA Layout

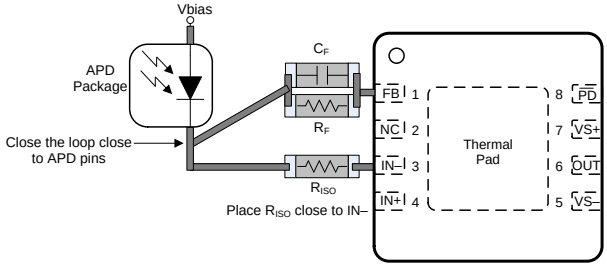


Figure 61. Improved TIA Layout

13 Device and Documentation Support

13.1 Device Support

13.1.1 Development Support

- *Wide Bandwidth Optical Front-end Reference Design*
- *LIDAR-Pulsed Time-of-Flight Reference Design Using High-Speed Data Converters*
- *LIDAR Pulsed Time of Flight Reference Design*

13.2 Documentation Support

13.2.1 Related Documentation

For related documentation see the following:

- *OPA855EVM User's Guide*
- *Transimpedance Considerations for High-Speed Amplifiers Application Report*
- *What You Need To Know About Transimpedance Amplifiers – Part 1*
- *What You Need To Know About Transimpedance Amplifiers – Part 2*
- *Training Video: How to Design Transimpedance Amplifier Circuits*
- *Training Video: High-Speed Transimpedance Amplifier Design Flow*
- *Training Video: How to Convert a TINA-TI Model into a Generic SPICE Model*

13.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

13.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

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13.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.7 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

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14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA855IDSGR	ACTIVE	WSON	DSG	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	855	Samples
OPA855IDSGT	ACTIVE	WSON	DSG	8	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	855	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF OPA855 :

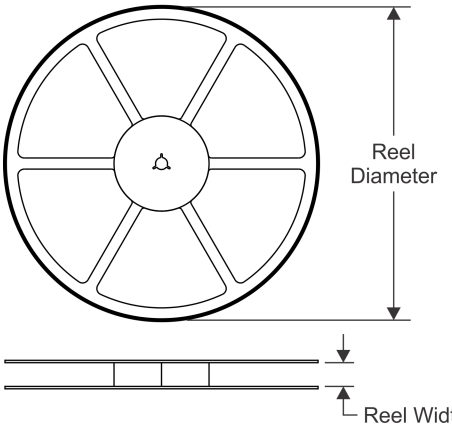
- Automotive : OPA855-Q1

NOTE: Qualified Version Definitions:

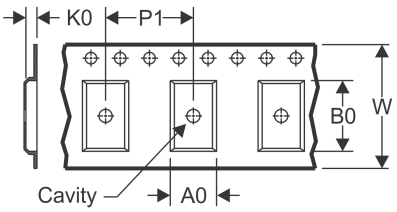
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

REEL DIMENSIONS

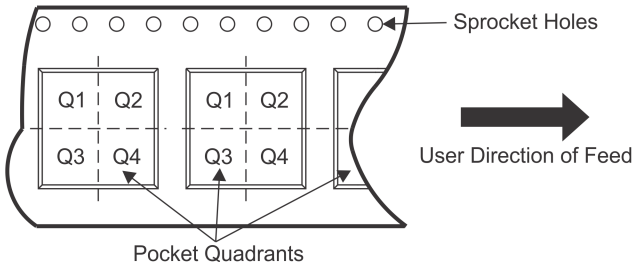


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

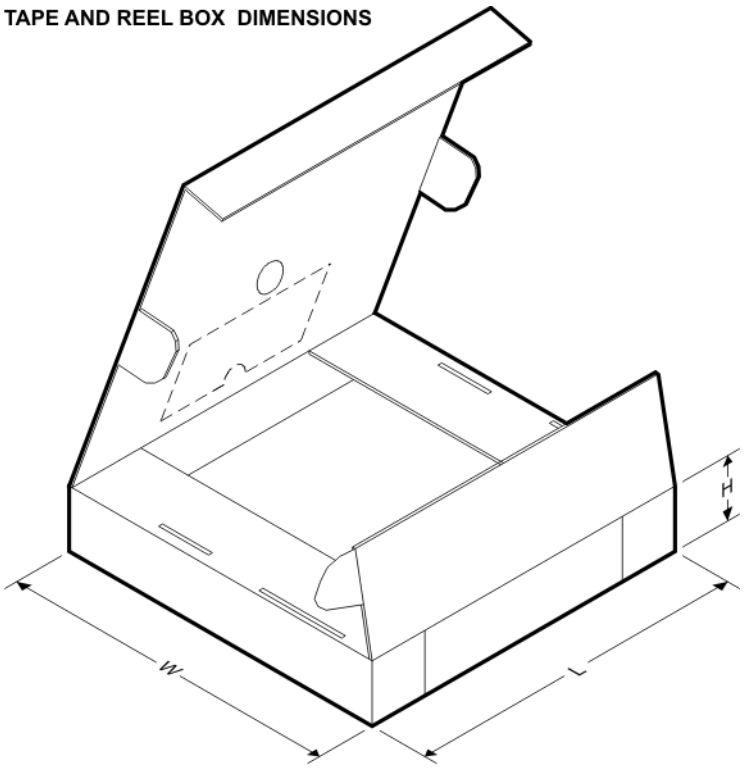
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA855IDSGR	WSON	DSG	8	3000	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2
OPA855IDSGT	WSON	DSG	8	250	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA855IDSGR	WSON	DSG	8	3000	210.0	185.0	35.0
OPA855IDSGT	WSON	DSG	8	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

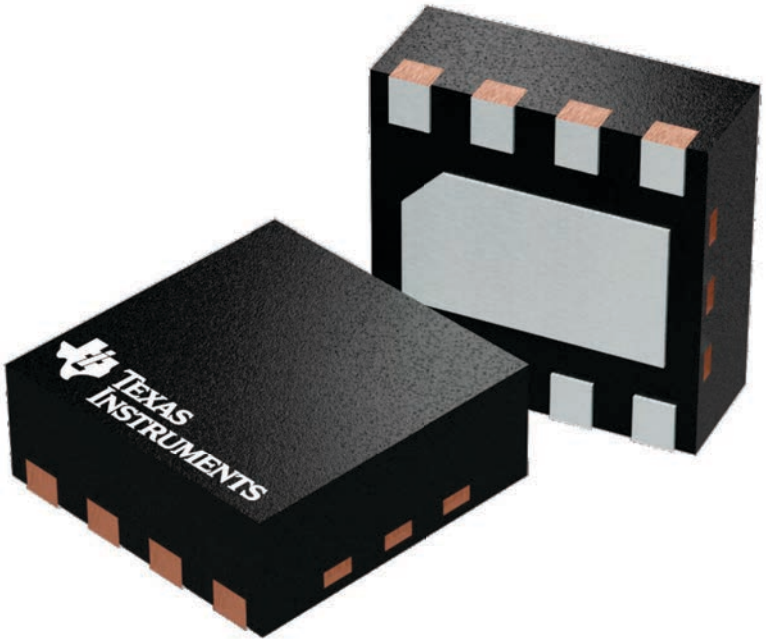
DSG 8

WSON - 0.8 mm max height

2 x 2, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



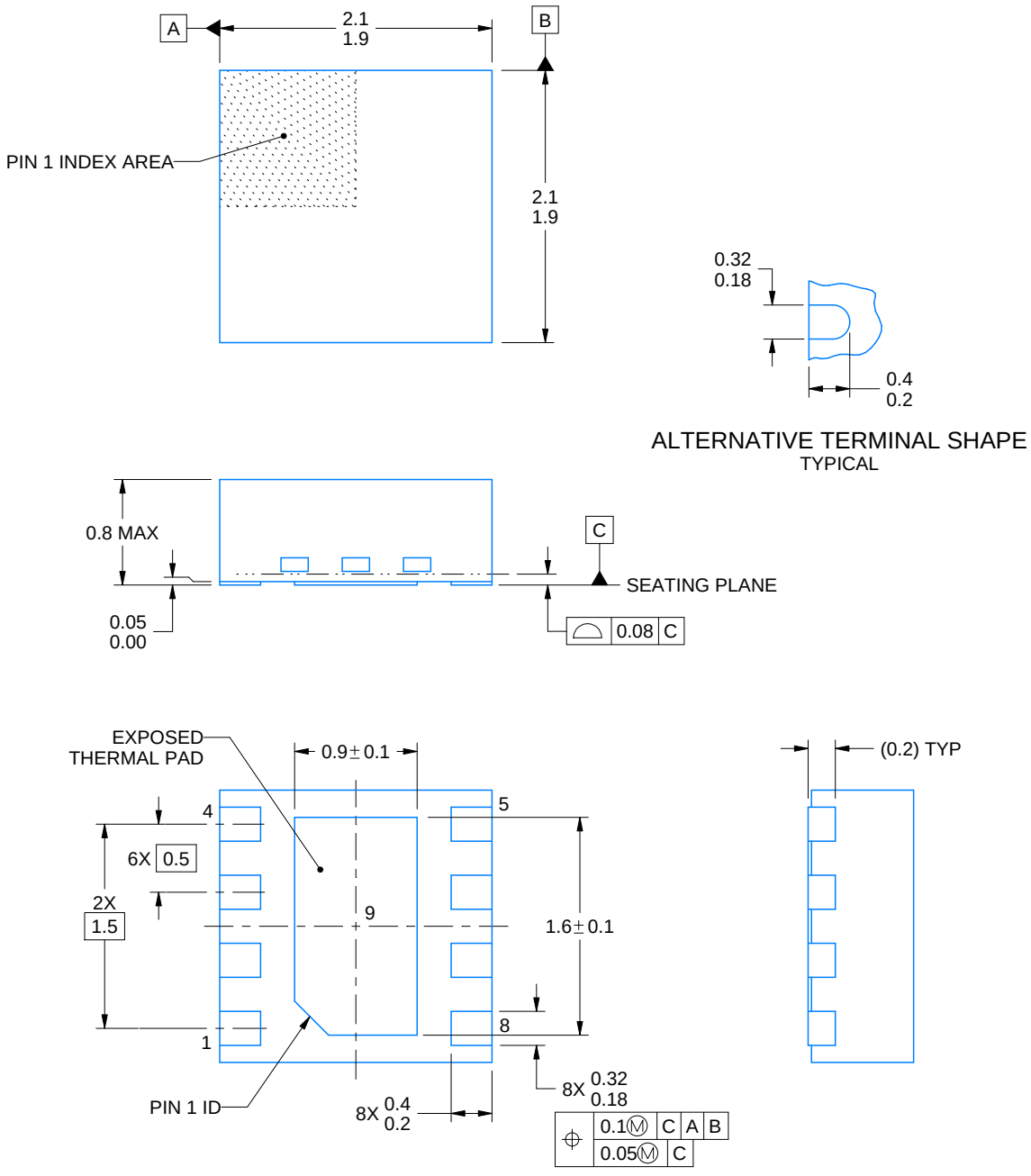
4224783/A

PACKAGE OUTLINE

DSG0008A

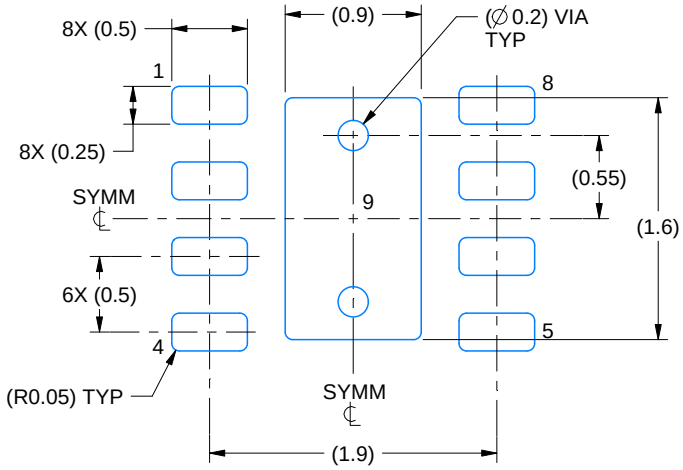
WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

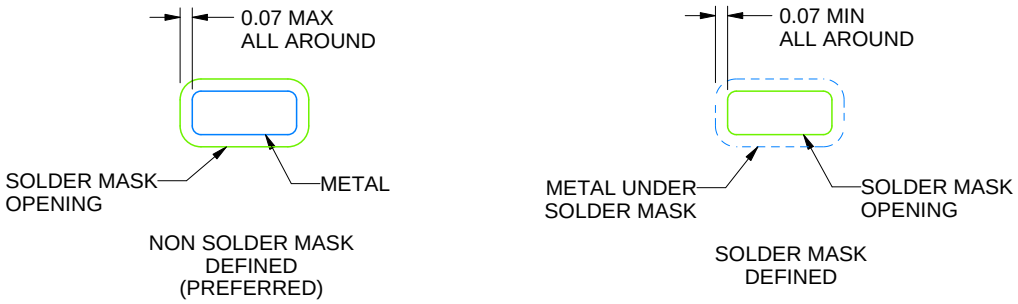


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4218900/D 04/2020

NOTES: (continued)

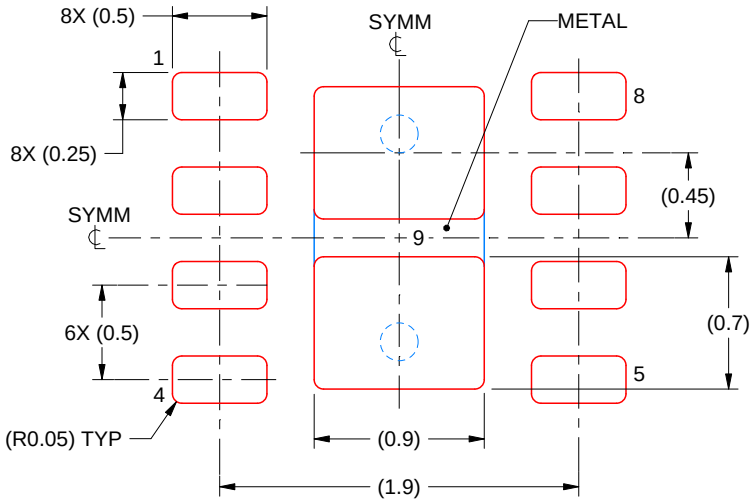
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DSG0008A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 9:
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:25X

4218900/D 04/2020

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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